



N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
 - 110 mΩ @ V_{GS} = 4.5V
 - 145 mΩ @ V_{GS} = 2.5V
 - 230 m Ω @ V_{GS} = 1.8V
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 1, 2 and 3)
- Qualified to AEC-Q101 Standards for High Reliability

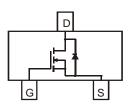
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)





Top View



Top View Internal Schematic

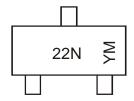
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2230U-7	SOT23	3000/Tape & Reel

Notes:

- ${\bf 1.\ No\ purposefully\ added\ lead.\ Halogen\ and\ Antimony\ Free.}$
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- $3.\ Product\ manufactured\ with\ Green\ Molding\ Compound\ and\ does\ not\ contain\ Halogens\ or\ Sb_2O_3\ Fire\ Retardants.$
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



22N = Marking Code YM = Date Code Marking Y = Year (ex: U = 2007) M = Month (ex: 9 = September)

Date Code Key

	Bato Codo I	,												
Ī	Year	2007	2008	2009	2010	201	1	201	2 2	2013	2014	2015	2016	2017
	Code	U	V	W	Х	Y		Z		Α	В	С	D	Е
Ī	Month	Jan	Feb	Mar	Apr	May	Jı	ın	Jul	Aug	Sep	Oct	Nov	Dec
ı	Code	1	2	3	4	5	(3	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	±12	V
Drain Current (Note 5)	I _D	2.0	Α
Pulsed Drain Current (Note 6)	I _{DM}	7	Α

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_{D}	600	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	208	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

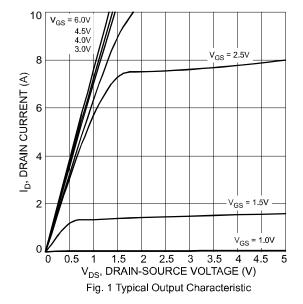
Electrical Characteristics @T_A = 25°C unless otherwise specified

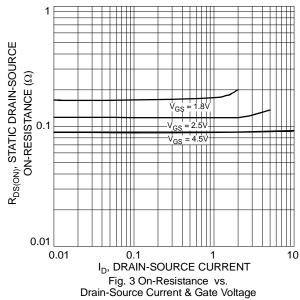
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20			V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	I _{DSS}			1	μΑ	$V_{DS} = 20V$, $V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}			±10	μΑ	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)			-			
Gate Threshold Voltage	$V_{GS(th)}$	0.5		1.0	V	$V_{DS} = V_{CS}, I_D = 250 \mu A$
			81 113 170	110 145 230	mΩ	$V_{GS} = 4.5V, I_D = 2.5A$
Static Drain-Source On-Resistance	R _{DS (ON)}					$V_{GS} = 2.5V, I_D = 1.5A$
						$V_{GS} = 1.8V, I_D = 1.0A$
Forward Transfer Admittance	Y _{fs}	_	5	_	S	$V_{DS} = 5V, I_D = 2.4A$
Diode Forward Voltage (Note 7)	V_{SD}		0.8	1.1	V	$V_{GS} = 0V, I_S = 1.05A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}		188		рF	V 40V V 0V
Output Capacitance	Coss		44		pF	$V_{DS} = 10V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}		30		рF	1 = 1:01/1112
Total Gate Charge	Q_g		2.3		nC	
Gate-Source Charge	Q_{gs}		0.3		nC	$V_{DS} = 10V, I_{D} = 11.6A$
Gate-Drain Charge	Q_{gd}		0.5		nC	
Turn-On Delay Time	t _{d(on)}		8	_		
Rise Time	t _r		3.8	_	ns	$V_{DD} = 10V$, $R_L = 10\Omega$
Turn-Off Delay Time	t _{d(off)}		19.6		115	$I_D = 1A$, $V_{GEN} = 4.5V$, $R_G = 6\Omega$
Fall Time	t _f	_	8.3	_		

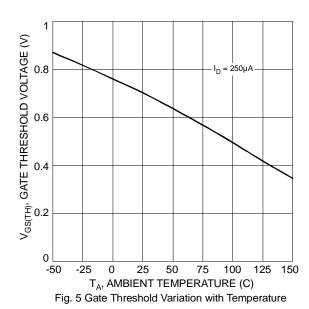
Notes:

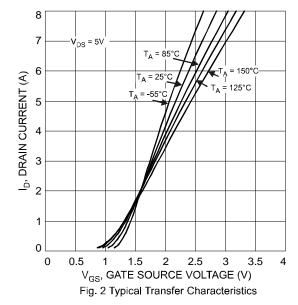
- 5. Device mounted on FR-4 PCB, or minimum recommended pad layout
- Repetitive rating, pulse width limited by junction temperature.
 Short duration pulse test used to minimize self-heating effect.











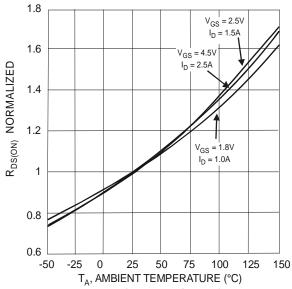
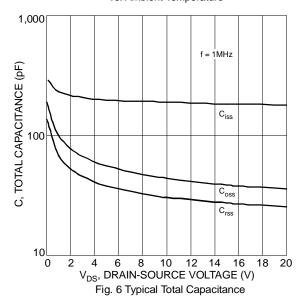
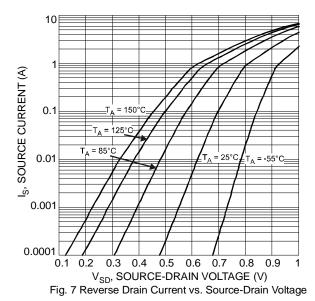
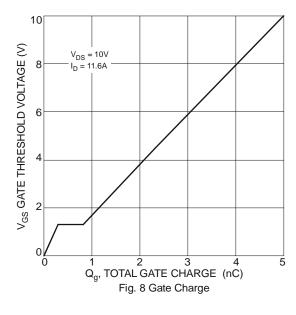


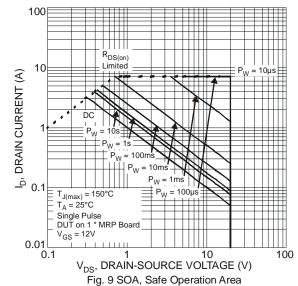
Fig. 4 Normalized Static Drain-Source On-Resistance vs. Ambient Temperature



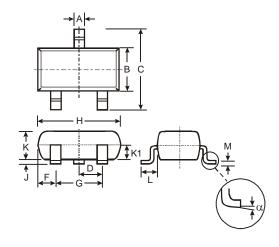








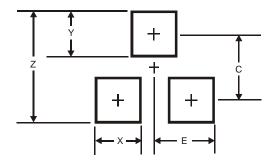
Package Outline Dimensions



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Η	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
M	0.085	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							



Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2012, Diodes Incorporated

www.diodes.com

5 of 5 DMN2230U Document number: DS31180 Rev. 5 - 2

单击下面可查看定价,库存,交付和生命周期等信息

>>Diodes Incorporated(达尔科技)